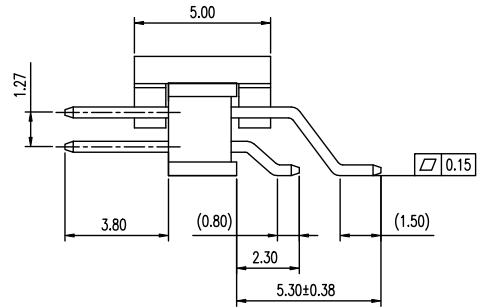
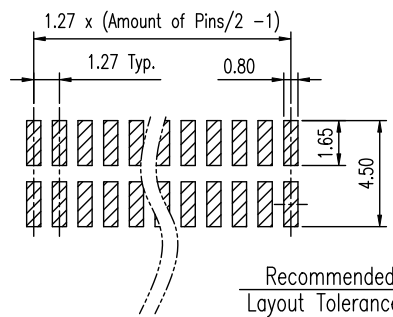
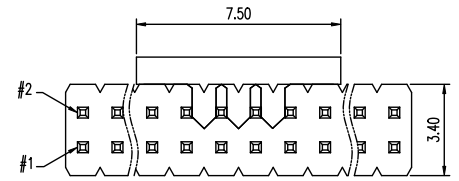
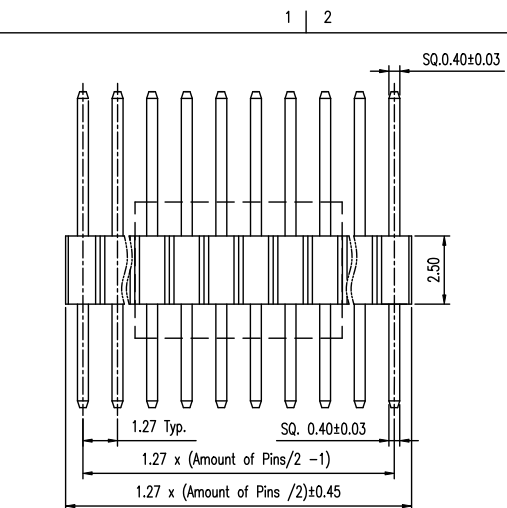


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NOTE:
 1. MATERIAL,
 HOUSING: HIGH TEMP PLASTIC, UL94-V0, BLACK
 TERMINAL: COPPER ALLOY , SQ=0.40±0.03MM
 2. FINISH:
 TERMINAL: GOLD AT CONTACT,
 G/F OVER 1um(40u")MIN Ni OVER ALL
 3. SPEC.:
 PRODUCT SPEC: GS-12-629
 PACKING SPEC: GS-14-1420
 4. THE HSG. WILL WITHSTAND EXPOSURE TO 260C
 PEAK TEMP. FOR 10 SEC. IN A CONVECTION, INFRA-RED
 OR VAPOR PHASE REFLOW OVEN.
 5. THE 0.15MM MIN. SOLDER PASTE IS RECOMMENDED
 FOR REFLOW SOLDERING.
 6. PRODUCT NUMBERING:
 20021122 - 0 0 0 XX X X LF
 LEAD FREE
 PLATING:
 1: GOLD FLASH ALL OVER
 4: 0.25um(10U")GOLD AT CONTACT
 8: 0.76um(30U")GOLD AT CONTACT
 PACKING
 D: TUBE+ CAP
 T: TUBE
 PIN COUNT
 6,10,12,14,...., 98
 (8 - 98 EVERY EVEN PIN)

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.X ± 0.38	projection	www.fciconnect.com
A	T09-1117	S.LIN	09/15/09		.XX ± 0.25		title 1.27X1.27MM BTB,HEADER UNSTROUED, SMT
B	T09-1155	S.LIN	12/03/09		.XXX ± 0.10		
C	T10-0014	S.LIN	01/28/10	angles	0° ± 2°		product family 585 size dwg no 20021122
D	T11-0029	S.LIN	11-06-14	dr	STERLING LIN 09/15/09		
				engr	STERLING LIN 09/15/09	scale	sheet
				chr	GARY HSIEH 09/15/09	A4	1 of 1
				appd	JOSEPH HSIA 09/15/09		
sheet index	revision	D					
	sheet	1					